

## STEP-UP DC/DC CONVERTER

NO.EA-298-190808

### OUTLINE

The R1207N Series are CMOS-based PWM control type step-up DC/DC converter ICs with low supply current. Each of these ICs consists of an NMOS FET, a diode, an oscillator, a PWM comparator, a voltage reference unit, an error amplifier, a current limit circuit, an under voltage lockout circuit (UVLO), an over-voltage protection circuit (OVP), a soft-start circuit, a Maxduty limit circuit, and a thermal shutdown protection circuit. This step-up DC/DC converter can be easily built with a few external components such as a coil, a resistor, and a capacitor. As the protection functions, the R1207N Series have a Lx peak current limit function, an over voltage protection (OVP) function, an under voltage lock out (UVLO) function and a thermal shutdown function.

The R1207N Series present the R1207N8xxA version that is optimized for the constant voltage power source, and the R1207N8xxB/C version that is optimized for driving the white LED with the constant current. The R1207N8xxB/C is an adjustable version that can change the LED brightness dynamically by using a 200Hz to 300kHz PWM signal toward the CE pin.

The R1207N Series are available in TSOT-23-6 package.

### FEATURES

- Input Voltage Range ..... 2.3V to 5.5V (R1207N8xxA)  
1.8V to 5.5V (R1207N8xxB/C)
- Supply Current ..... Typ. 800 $\mu$ A
- Standby Current ..... Max. 5 $\mu$ A
- Feedback Voltage ..... 1.0V $\pm$ 1.5% (R1207N8xxA)  
0.2V $\pm$ 10mV (R1207N8xxB)  
0.4V $\pm$ 10mV (R1207N8xxC)
- Oscillator Frequency ..... Typ. 1.2MHz
- Maximum Duty Cycle ..... Typ. 91%
- UVLO Function ..... Typ. 2.0V (Hys. Typ. 0.2V) (R1207N8xxA)  
Typ. 1.6V (Hys. Typ. 0.1V) (R1207N8xxB/C)
- Lx Current Limit Function ..... Select from 350mA, 700mA
- Over Voltage Protection ..... Typ. 25V
- LED dimming control (R1207N8xxB/C) ..... by external PWM signal (Frequency 200Hz to 300kHz)
- Thermal Protection Function ..... Typ. 150 $^{\circ}$ C (Hys. Typ. 50 $^{\circ}$ C)
- Switch ON Resistance ..... Typ. 1.35 $\Omega$
- Package ..... TSOT-23-6
- Ceramic capacitors are recommended

### APPLICATION

- Constant Voltage Power Source for portable equipment
- OLED power supply for portable equipment
- White LED Backlight for portable equipment

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**R1207N**

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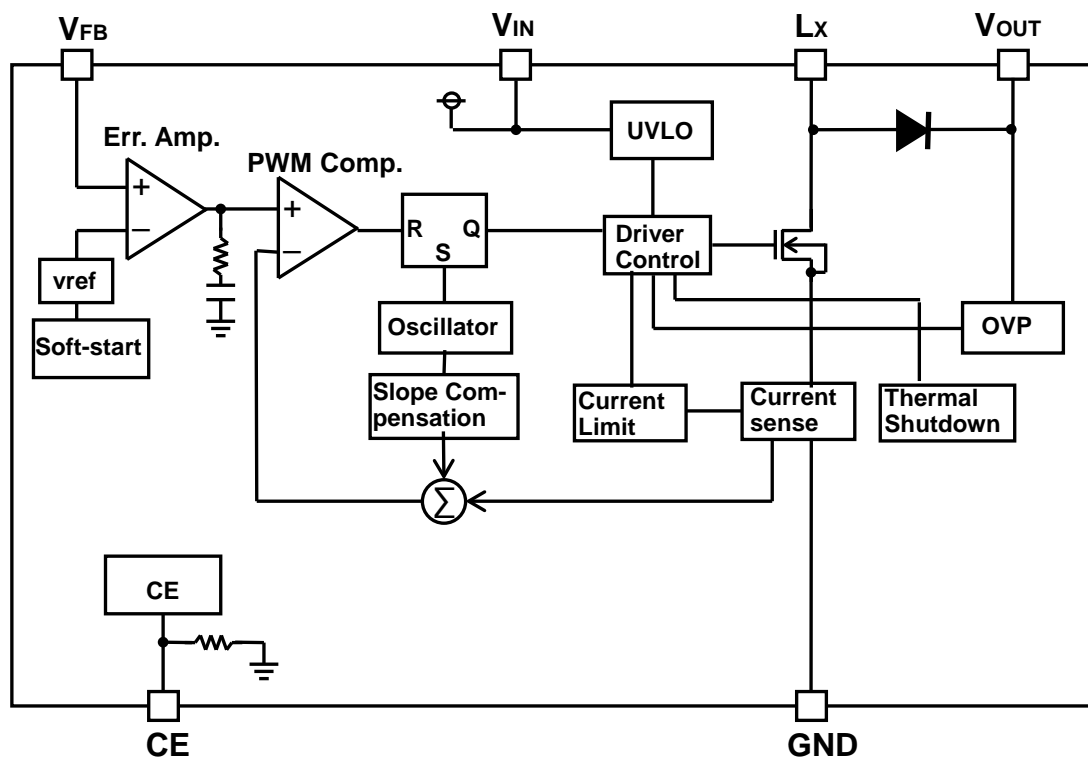
**SELECTION GUIDE**

The OVP threshold voltage, current limit and  $V_{FB}$ /Auto discharge are user-selectable options.

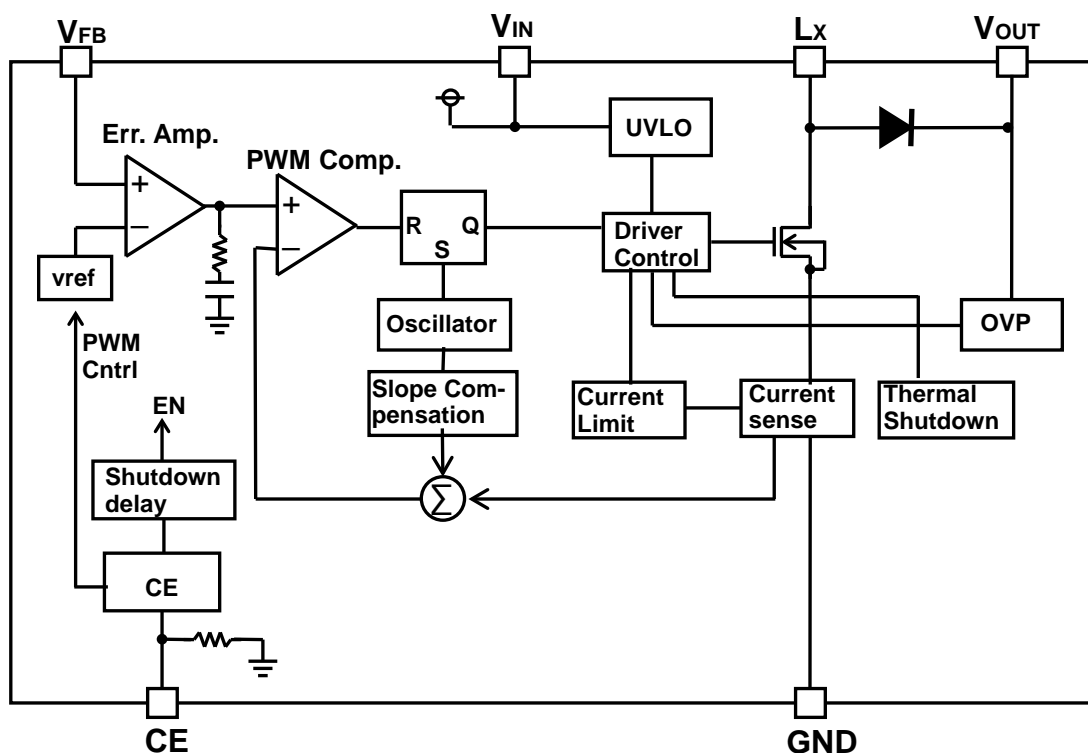
Product Name	Package	Quantity per Reel	Pb Free	Halogen Free
R1207N8x3*-TR-FE	TSOT-23-6	3,000 pcs	Yes	Yes
<p>x : Designation of current limit. (1) 350mA (2) 700mA</p> <p>* : Designation of <math>V_{FB}</math>. (A) 1.0V (B) 0.2V (C) 0.4V</p>				

## BLOCK DIAGRAMS

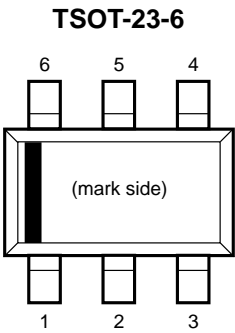
R1207N8xxA



R1207N8xxB/C



PIN DESCRIPTIONS



TSOT-23-6

Pin No	Symbol	Pin Description
1	L <sub>X</sub>	Switching Pin (Open Drain Output)
2	GND	Ground Pin
3	V <sub>FB</sub>	Feedback Pin
4	CE	Chip Enable Pin ("H" Active)
5	V <sub>OUT</sub>	Output Pin
6	V <sub>IN</sub>	Input Pin

## ABSOLUTE MAXIMUM RATINGS

GND=0V

Symbol	Item	Rating	Unit
$V_{IN}$	$V_{IN}$ Pin Voltage	−0.3 to 6.5	V
$V_{CE}$	CE Pin Voltage	−0.3 to 6.5	V
$V_{FB}$	$V_{FB}$ Pin Voltage	−0.3 to 6.5	V
$V_{OUT}$	$V_{OUT}$ Pin Voltage	−0.3 to 28	V
$V_{LX}$	$L_X$ Pin Voltage	−0.3 to 28	V
$I_{LX}$	$L_X$ Pin Current	1000	mA
$P_D$	Power Dissipation (TSOT-23-6)*	460	mW
$T_j$	Junction Temperature Range	−40 to 125	°C
$T_{stg}$	Storage Temperature Range	−55 to 125	°C

\*) Refer to *POWER DISSIPATION* for detailed information.

### ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause permanent damage and may degrade the life time and safety for both device and system using the device in the field. The functional operation at or over these absolute maximum ratings is not assured.

## RECOMMENDED OPERATING CONDITIONS

Symbol	Item	Rating		Unit
$V_{IN}$	Operating Input Voltage	R1207N8xxA	2.3 to 5.5	V
		R1207N8xxB/C	1.8 to 5.5	V
$T_a$	Operating Temperature Range	−40 to 85		°C

### RECOMMENDED OPERATING CONDITIONS

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if they are used over such conditions by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

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**ELECTRICAL CHARACTERISTICS****R1207N**

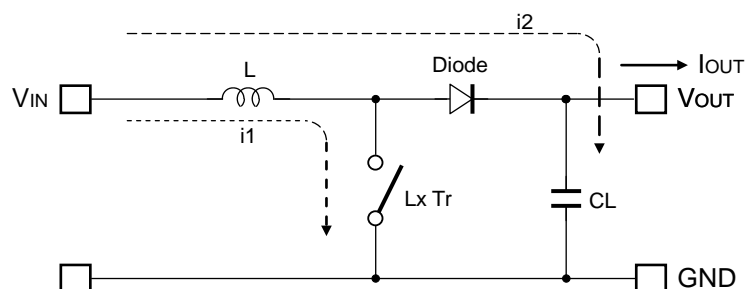
(Ta=25°C)

Symbol	Item	Conditions		Min.	Typ.	Max.	Unit
I <sub>DD</sub>	Supply Current	V <sub>IN</sub> =5.5V, V <sub>FB</sub> =0V, L <sub>X</sub> at no load			0.8	1.2	mA
I <sub>standby</sub>	Standby Current	V <sub>IN</sub> =5.5V, V <sub>CE</sub> =0V			1.0	5.0	μA
V <sub>UVLO1</sub>	UVLO Detector Threshold	V <sub>IN</sub> falling	R1207N8xxA	1.9	2.0	2.1	V
			R1207N8xxB/C	1.5	1.6	1.7	
V <sub>UVLO2</sub>	UVLO Released Voltage	V <sub>IN</sub> rising	R1207N8xxA		V <sub>UVLO1</sub> +0.2	2.3	V
			R1207N8xxB/C		V <sub>UVLO1</sub> +0.1	1.8	
V <sub>CEH</sub>	CE Input Voltage "H"	V <sub>IN</sub> =5.5V		1.5			V
V <sub>CEL</sub>	CE Input Voltage "L"					0.5	V
R <sub>CE</sub>	CE Pull Down Resistance				1200		kΩ
V <sub>FB</sub>	V <sub>FB</sub> Voltage Accuracy	V <sub>IN</sub> =3.6V	R1207N8xxA	0.985	1.000	1.015	V
			R1207N8xxB	0.19	0.2	0.21	
			R1207N8xxC	0.39	0.4	0.41	
ΔV <sub>FB</sub> /ΔT <sub>a</sub>	V <sub>FB</sub> Voltage Temperature Coefficient	V <sub>IN</sub> =3.6V, -40°C ≤ T <sub>a</sub> ≤ 85°C			±150		ppm/°C
I <sub>FB</sub>	V <sub>FB</sub> Input Current	V <sub>IN</sub> =5.5V, V <sub>FB</sub> =0V or 5.5V		-0.1		0.1	μA
t <sub>start</sub>	Soft-start Time		R1207N8xxB/C		2.0	3.0	ms
R <sub>ON</sub>	FET ON Resistance	I <sub>LX</sub> =100mA			1.35		Ω
I <sub>OFF</sub>	FET Leakage Current	V <sub>LX</sub> =24V				3.0	μA
I <sub>LIM</sub>	FET Current Limit		R1207N81xx	250	350	450	mA
			R1207N82xx	500	700	900	
V <sub>F</sub>	Diode Forward Voltage	I <sub>SW</sub> =100mA			0.8		V
I <sub>DIODEleak</sub>	Diode Leakage Current	V <sub>OUT</sub> =24V, V <sub>LX</sub> =0V				10	μA
f <sub>osc</sub>	Oscillator Frequency	V <sub>IN</sub> =3.6V, V <sub>FB</sub> =0V		1000	1200	1400	kHz
Maxduty	Maximum Duty Cycle	V <sub>IN</sub> =3.6V, V <sub>FB</sub> =0V		86	91		%
V <sub>OVP1</sub>	OVP Detect Voltage	V <sub>IN</sub> =3.6V, V <sub>OUT</sub> rising		24.2	25	25.8	V
V <sub>OVP2</sub>	OVP Release Voltage	V <sub>IN</sub> =3.6V, V <sub>OUT</sub> falling			V <sub>OVP1</sub> -1.8		V
T <sub>TSD</sub>	Thermal Shutdown Detect Temperature	V <sub>IN</sub> =3.6V			150		°C
T <sub>TSR</sub>	Thermal Shutdown Release Temperature	V <sub>IN</sub> =3.6V			100		°C

## THEORY OF OPERATION

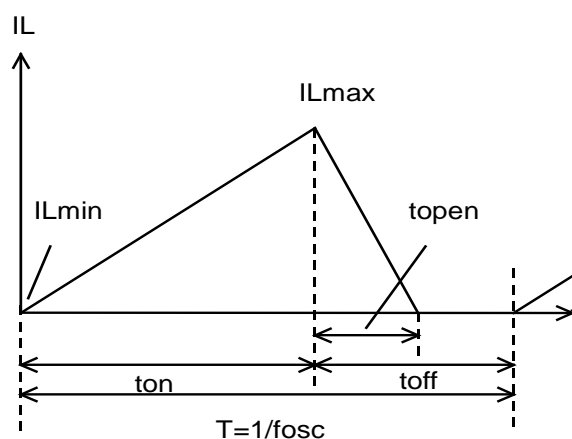
### Operation of Step-Up DC/DC Converter and Output Current

#### <Basic Circuit>

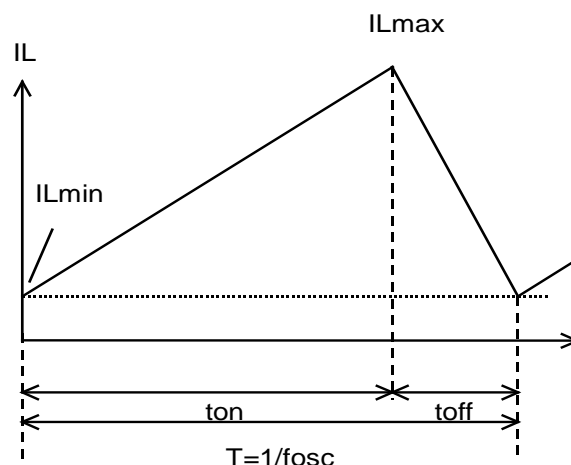


#### <Current through L>

##### Discontinuous mode



##### Continuous mode



There are two operation modes of the step-up PWM control-DC/DC converter. That is the continuous mode and discontinuous mode by the continuousness inductor.

When the transistor turns ON, the voltage of inductor L becomes equal to  $V_{IN}$  voltage. The increase value of inductor current ( $i1$ ) will be

$$\Delta i1 = V_{IN} \times t_{on} / L \dots\dots\dots \text{Formula 1}$$

As the step-up circuit, during the OFF time (when the transistor turns OFF) the voltage is continually supply from the power supply. The decrease value of inductor current ( $i2$ ) will be

$$\Delta i2 = (V_{OUT} - V_{IN}) \times t_{open} / L \dots\dots\dots \text{Formula 2}$$

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At the PWM control-method, the inductor current become continuously when  $t_{open}=t_{off}$ , the DC/DC converter operate as the continuous mode.

In the continuous mode, the variation of current of  $i_1$  and  $i_2$  is same at regular condition.

$$V_{IN} \times t_{on} / L = (V_{OUT} - V_{IN}) \times t_{off} / L \dots\dots\dots \text{Formula 3}$$

The duty at continuous mode will be

$$\text{duty (\%)} = t_{on} / (t_{on} + t_{off}) = (V_{OUT} - V_{IN}) / V_{OUT} \dots\dots\dots \text{Formula 4}$$

The average of inductor current at  $t_f = t_{off}$  will be

$$I_L(\text{Ave.}) = V_{IN} \times t_{on} / (2 \times L) \dots\dots\dots \text{Formula 5}$$

If the input voltage = output voltage, the  $I_{OUT}$  will be

$$I_{OUT} = V_{IN}^2 \times t_{on} / (2 \times L \times V_{OUT}) \dots\dots\dots \text{Formula 6}$$

If the  $I_{OUT}$  value is large than above the calculated value (Formula 6), it will become the continuous mode, at this status, the peak current ( $I_{Lmax}$ ) of inductor will be

$$I_{Lmax} = I_{OUT} \times V_{OUT} / V_{IN} + V_{IN} \times t_{on} / (2 \times L) \dots\dots\dots \text{Formula 7}$$

$$I_{Lmax} = I_{OUT} \times V_{OUT} / V_{IN} + V_{IN} \times T \times (V_{OUT} - V_{IN}) / (2 \times L \times V_{OUT}) \dots\dots\dots \text{Formula 8}$$

The peak current value is larger than the  $I_{OUT}$  value. In case of this, selecting the condition of the input and the output and the external components by considering of  $I_{Lmax}$  value.

The explanation above is based on the ideal calculation, and the loss caused by  $L_x$  switch and the external components are not included.

The actual maximum output current will be between 50% and 80% by the above calculations. Especially, when the  $I_L$  is large or  $V_{IN}$  is low, the loss of  $V_{IN}$  is generated with on resistance of the switch. Moreover, it is necessary to consider  $V_f$  of the diode (approximately 0.8V) about  $V_{OUT}$ .

● **Soft-Start (R1207N8xxB/C)**

The output and reference of the error amplifier start from 0V and the reference gradually rises up to 1.0V. After the softstart time ( $T_{ss}$ ), output voltage rise up to the setting voltage.

The output of the error amplifier starts from 0V and the inrush current is suppressed when starting by the CE pin "H" input. Moreover, the inrush current can be suppressed by gradually enlarging Duty of the PWM signal to the CE pin.

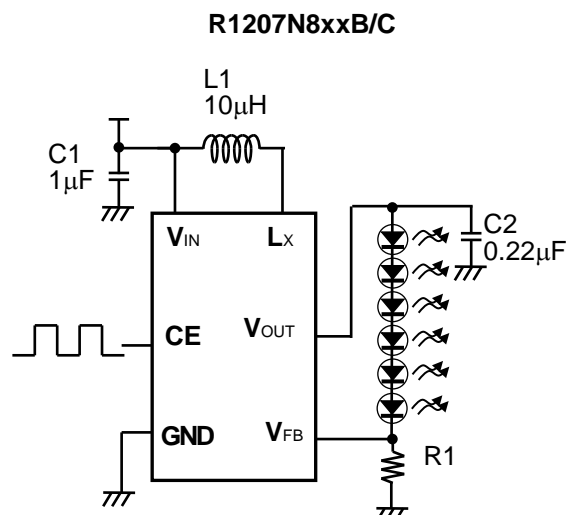
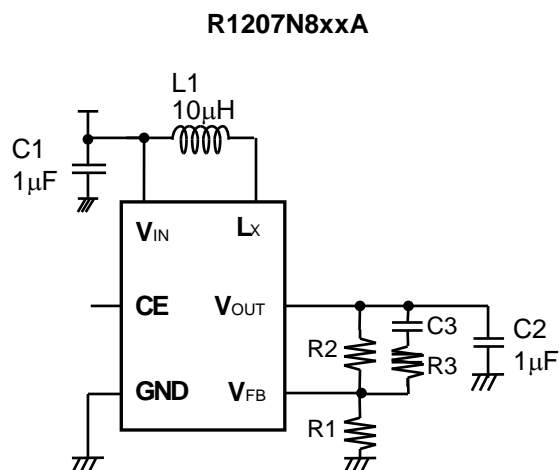
● **Current Limit Function**

Current limit function monitors the over current and if it reaches the peak current, it will turn off the driver. When the over current decreases, it will restart oscillation and will restart the monitoring.



## APPLICATION INFORMATION

### Typical Applications



### ● Inductor Selection

The peak current of the inductor at normal mode can be estimated as the next formula when the efficiency is 80%.

$$I_{Lmax} = 1.25 \times I_{OUT} \times V_{OUT} / V_{IN} + 0.5 \times V_{IN} \times (V_{OUT} - V_{IN}) / (L \times V_{OUT} \times f_{osc})$$

In the case of start-up or dimming control by CE pin, inductor transient current flows, and the peak current of it must be equal or less than the current limit of the IC. The peak current should not be beyond the rated current of the inductor. The recommended inductance value is 10μH - 22μH.

**Table 1 Peak current value in each condition**

Condition				
V <sub>IN</sub> (V)	V <sub>OUT</sub> (V)	I <sub>OUT</sub> (mA)	L (μH)	I <sub>Lmax</sub> (mA)
3	14	20	10	215
3	14	20	22	160
3	21	20	10	280
3	21	20	22	225

**Table 2 Recommended inductors**

L (μH)	Part No.	Rated Current (mA)	Size (mm)
10	LQH32CN100K53	450	3.2x2.5x1.55
10	LQH2MC100K02	225	2.0x1.6x0.9
10	VLF3010A-100	490	2.8x2.6x0.9
10	VLS252010-100	520	2.5x2.0x1.0
22	LQH32CN220K53	250	3.2x2.5x1.55
22	LQH2MC220K02	185	2.0x1.6x0.9
22	VLF3010A-220	330	2.8x2.6x0.9

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**● Capacitor Selection**

Set 1 $\mu$ F or more value bypass capacitor C1 between V<sub>IN</sub> pin and GND pin as close as possible.

**R1207NxxxA**

Set 1 $\mu$ F – 4.7 $\mu$ F or more capacitor C2 between V<sub>OUT</sub> and GND pin.

**Table 3-A Recommended components for R1207NxxxA**

	Rated voltage(V)	Part No.
C1	6.3	CM105B105K06
C2	25	GRM21BR11E105K
C3	25	22pF
R1		For V <sub>OUT</sub> Setting
R2		For V <sub>OUT</sub> Setting
R3		2k $\Omega$

If the transient drop of output voltage by the load fluctuation is large and exceeds the allowable range in above setting, refer to Table 3-B to change the capacitors of C2 and C3 for the response improvement and the transient voltage drop reduction.

**Table 3-B Recommended components for R1207xxxxA**

	Rated voltage(V)	Part No.
C1	6.3	CM105B105K06
C2	50	GRM31CR71H475M
C3	25	220pF
R1		For V <sub>OUT</sub> Setting
R2		For V <sub>OUT</sub> Setting
R3		2k $\Omega$

**R1207NxxxB/C**

Set 0.22 $\mu$ F or more capacitor C2 between V<sub>OUT</sub> and GND pin. (R1207N8xxB)

Set 0.47 $\mu$ F or more capacitor C2 between V<sub>OUT</sub> and GND pin. (R1207N8xxC)

Note the V<sub>OUT</sub> that depends on LED used, and select the rating of V<sub>OUT</sub> or more.

**Table 4 Recommended components for R1207NxxxB/C**

	Rated voltage(V)	Part No.
C1	6.3	CM105B105K06
C2	25	GRM21BR11E224
	25	C2012X7R1E474K
	50	GRM21BR71H224

### ● External Components Setting

If the  $V_{OUT}$  spike noise is high, it may influence on the  $V_{FB}$  pin to cause the operation of R1205x8xxA unstable. To reduce the noise coming into  $V_{FB}$  pin, please place a 1k $\Omega$  to 5k $\Omega$  resistor in R3 in Fig. 1.

### ● Application of Using 5.5V or more Power Supply

Other than the IC power supply, if there is a power supply greater than 5.5V, the high power output can be achieved by using the power supply as an inductor power supply. In this case, please place a capacitor between an inductor power supply and GND (shown in Fig. 2) aside from a bypass capacitor between the  $V_{IN}$  pin and GND of the IC.

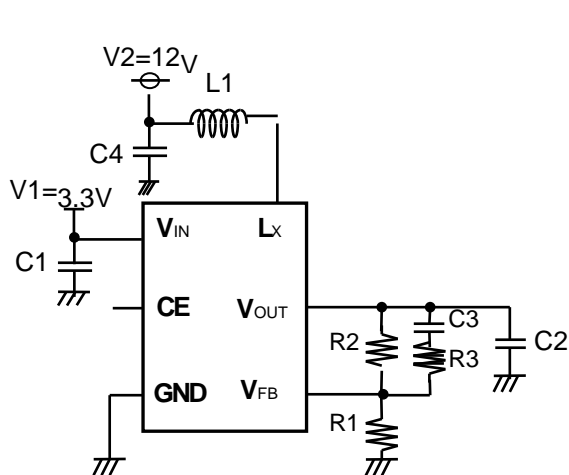


Fig. 1 R1207N8xxA

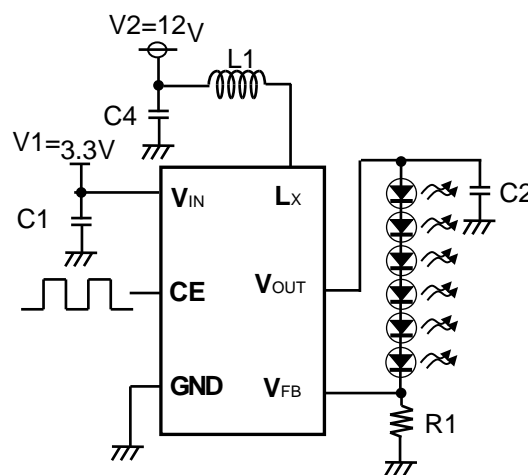


Fig. 2 R1207N8xxB/C

### ● The Method of Output Voltage Setting (R1207N8xxA)

The output voltage ( $V_{OUT}$ ) can be calculated with divider resistors ( $R1$  and  $R2$ ) values as the following formula:

$$\text{Output Voltage } (V_{OUT}) = V_{FB} \times (R1 + R2) / R1$$

The total value of  $R1$  and  $R2$  should be equal or less than 300k $\Omega$ . Make the  $V_{IN}$  and GND line sufficient. The large current flows through the  $V_{IN}$  and GND line due to the switching. If this impedance ( $V_{IN}$  and GND line) is high, the internal voltage of the IC may shift by the switching current, and the operating may become unstable. Moreover, when the built-in  $Lx$  switch is turn OFF, the spike noise caused by the inductor may be generated. As a result of this, recommendation voltage rating of capacitor ( $C2$ ) value is equal 1.5 times larger or more than the setting output voltage.

### ● LED Current setting (R1207N8xxB/C)

When CE pin input is "H" (Duty=100%), LED current can be set with feedback resistor ( $R1$ )

$$I_{LED} = V_{FB} / R1$$

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### ● LED Dimming Control (R1207N8xxB/C)

The LED brightness can be controlled by inputting the PWM signal to the CE pin. If the CE pin input is "L" in the fixed time (Typ.0.5ms), the IC becomes the standby mode and turns OFF LEDs.

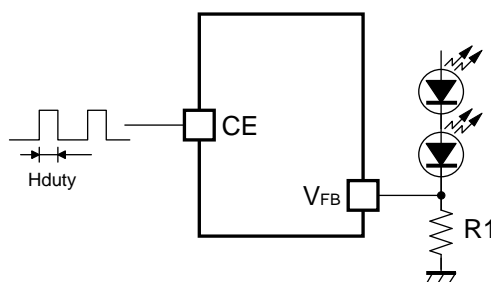
The current of LEDs can be controlled by Duty of the PWM signal of the input CE pin. The current of LEDs when High-Duty of the CE input is "Hduty" reaches the value as calculatable following formula.

$$I_{LED} = Hduty \times V_{FB} / R1$$

The frequency of the PWM signal is using the range between 200Hz to 300kHz.

When controlling the LED brightness by the PWM signal of 5kHz or less, R1207N8xxB/C are recommended to avoid discharge function during dimming control.

When controlling the LED brightness by the PWM signal of 20kHz or less, the increasing or decreasing of the inductor current might make a sound in the hearable sound wave area. In that case, please use the PWM signal in the high frequency area.



**Dimming Control by CE Pin Input**

### ● Low luminance Dimming Accuracy (R1207N8xxC)

Low luminance Dimming filtered  $V_{FB}$  voltage tolerance depends on the offset voltage of the internal DC/DC converter. By this offset voltage, some voltage difference may be generated between  $V_{REF}$  voltage and  $V_{FB}$  voltage. Low luminance Dimming Accuracy is shown below.

**Low luminance Dimming Accuracy for R1207N8xxC (R1=20ohm)**

The duty of a PWM signal for the CE pin	I <sub>LED</sub> Min.	I <sub>LED</sub> Max.
3.5% (Frequency = 20kHz ~ 300kHz)	0.01mA <sup>*2</sup>	2.1mA <sup>*2</sup>

<sup>\*2</sup> guaranteed by design engineering (Ta=25 °C)

## TECHNICAL NOTES

### ● Current Path on PCB

The current paths in an application circuit are shown in Fig. 3 and 4.

A current flows through the paths shown in Fig. 3 at the time of MOSFET-ON, and shown in Fig. 4 at the time of MOSFET-OFF. In the paths pointed with red arrows in Fig. 4, current flows just in MOSFET-ON period or just in MOSFET-OFF period. Parasitic impedance / inductance and the capacitance of these paths influence stability of the system and cause noise outbreak. So please minimize this side effect. In addition, please shorten the wiring of other current paths shown in Fig. 3 and 4 except for the paths of LED load.

### ● Layout Guide for PCB

- Please shorten the wiring of the input capacitor (C1) between  $V_{IN}$  pin and GND pin of IC. The GND pin should be connected to the strong GND plane.
- The area of  $L_x$  land pattern should be smaller.
- Please put output capacitor (C2) close to the  $V_{OUT}$  pin.
- Please make the GND side of output capacitor (C2) close to the GND pin of IC.

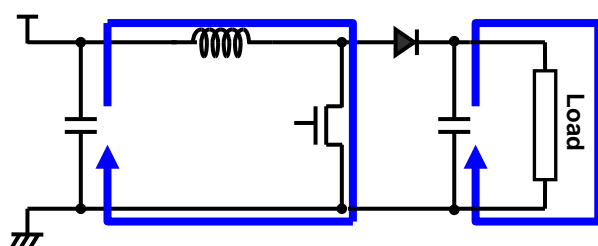


Fig. 3 MOSFET-ON

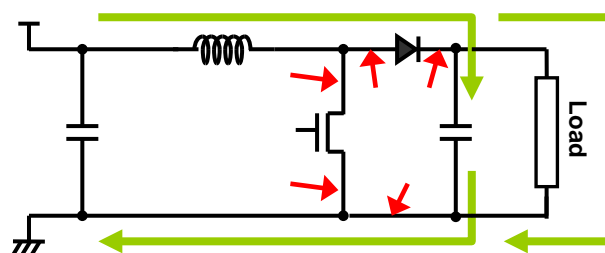
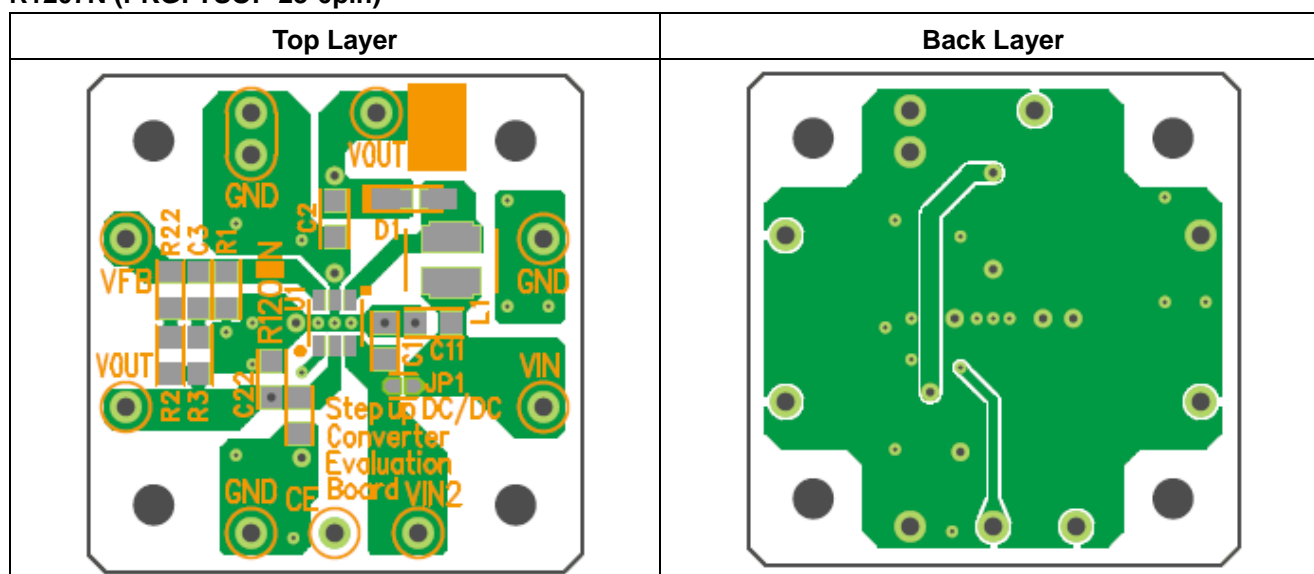


Fig. 4 MOSFET-OFF

### ● PCB Layout

R1207N (PKG: TSOP-23-6pin)

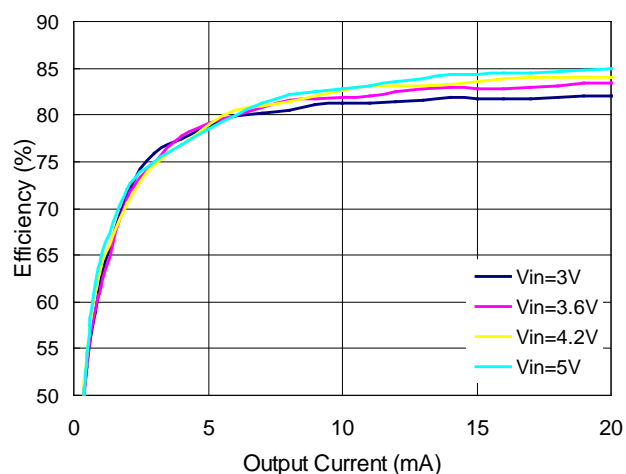


U1-■ indicates the position of No.1 pin.

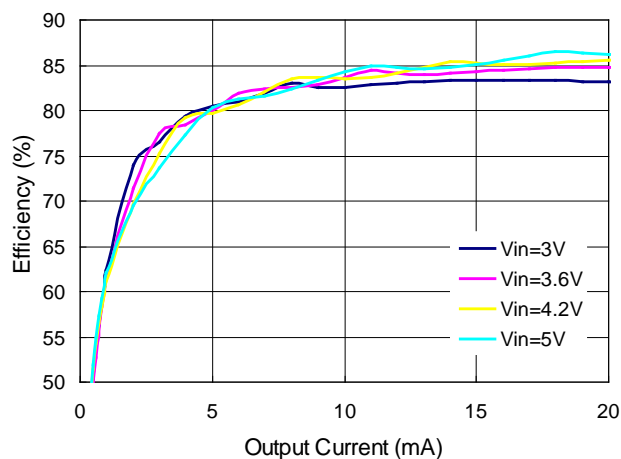
## TYPICAL CHARACTERISTICS

### 1) Efficiency vs. Output Current Characteristics (R1207N823A)

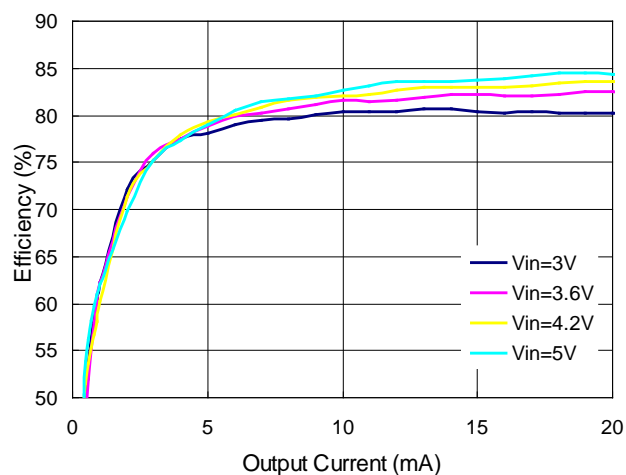
$V_{OUT}=10V$ ,  $L=10\mu H$  (LQH32CN100K53)



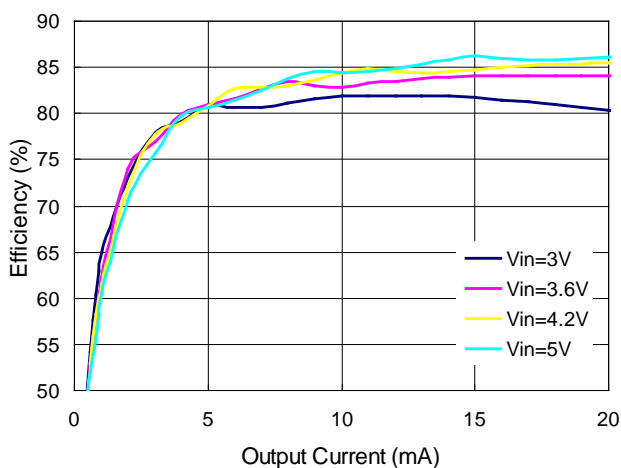
$V_{OUT}=10V$ ,  $L=22\mu H$  (LQH32CN220K53)



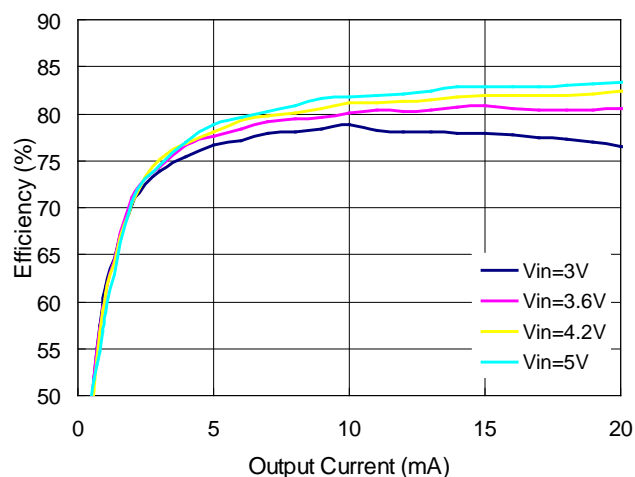
$V_{OUT}=15V$ ,  $L=10\mu H$  (LQH32CN100K53)



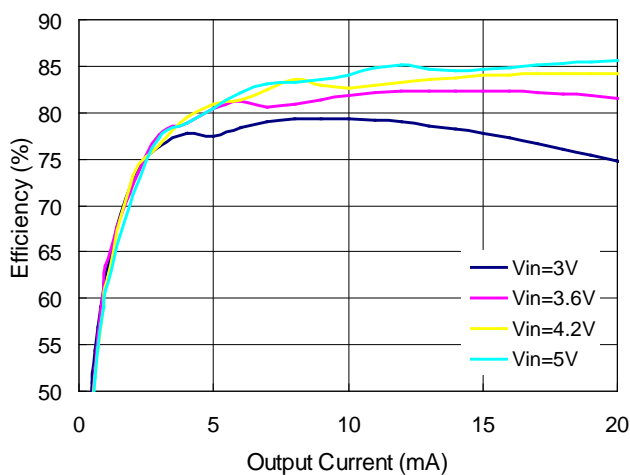
$V_{OUT}=15V$ ,  $L=22\mu H$  (LQH32CN220K53)

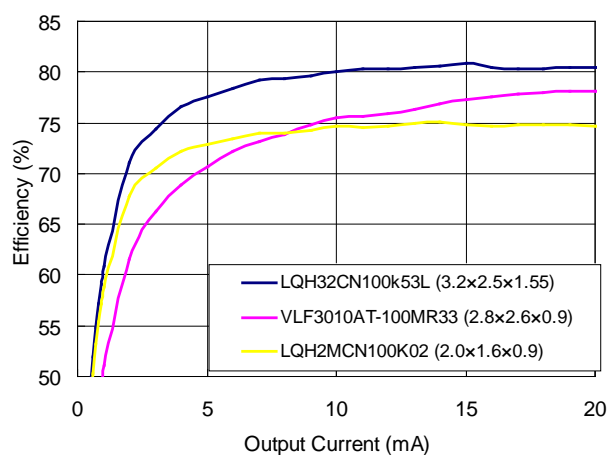
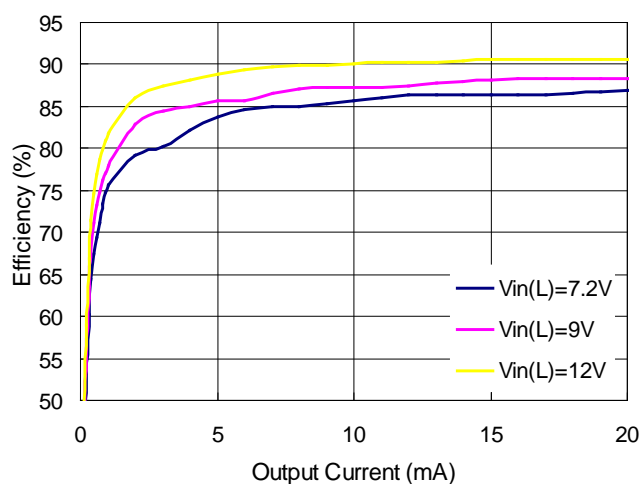
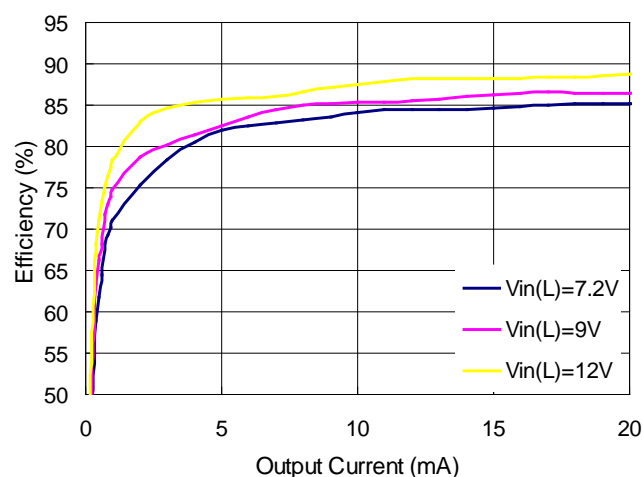
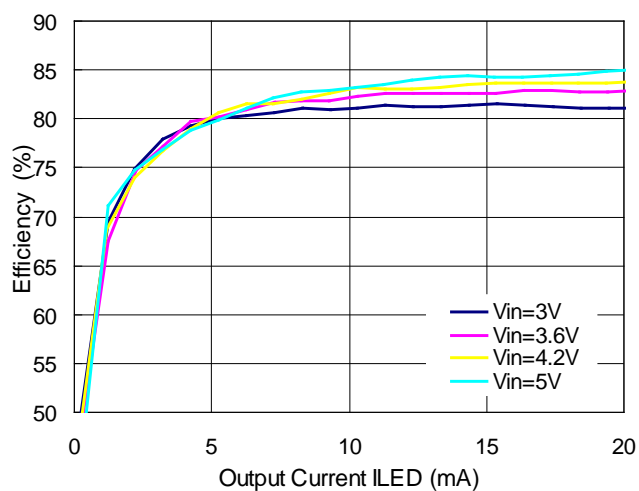
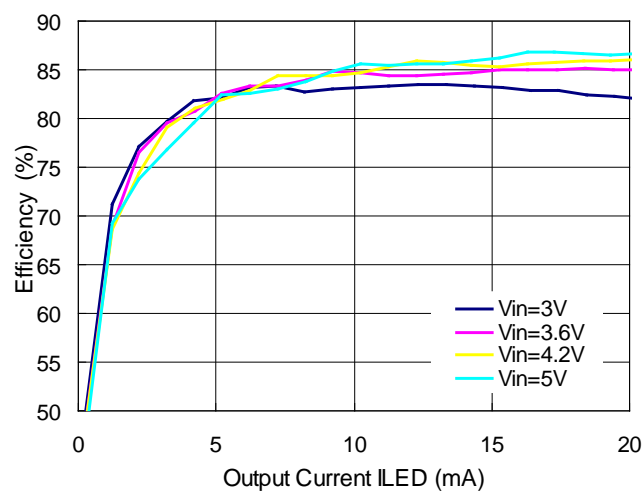


$V_{OUT}=20V$ ,  $L=10\mu H$  (LQH32CN100K53)

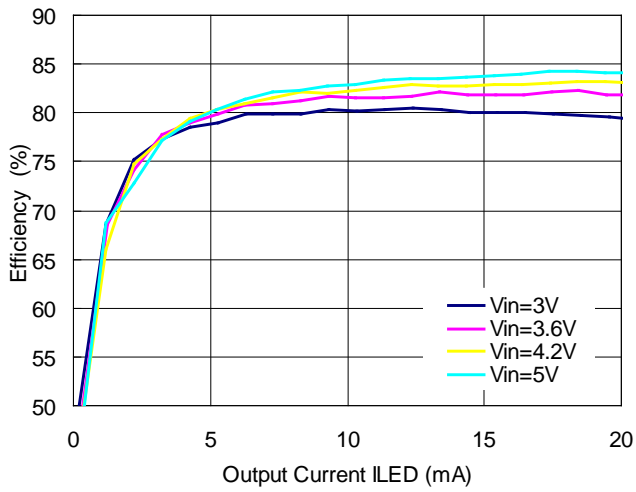


$V_{OUT}=20V$ ,  $L=22\mu H$  (LQH32CN220K53)

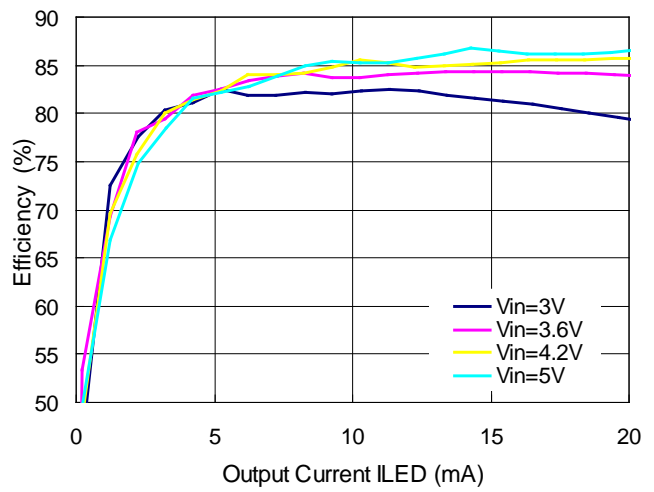


**$V_{OUT}=20V$ ,  $V_{IN}=3.6V$** **Typical Applications with Using 5.5V or Greater** **$V_{OUT}=15V$ ,  $L=10\mu H$  (LQH32CN100K53)** **$V_{OUT}=20V$ ,  $L=10\mu H$  (LQH32CN100K53)****2) Efficiency vs. Output Current Characteristics (R1207N823B/C)****4LED,  $L=10\mu H$  (LQH32CN100K53)****4LED,  $L=22\mu H$  (LQH32CN220K53)**

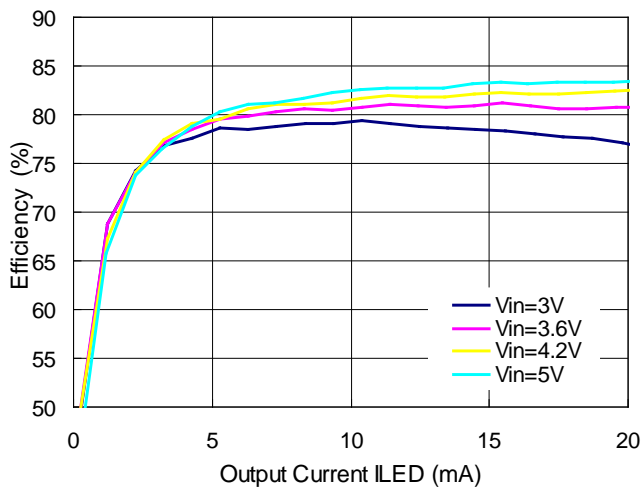
**5LED, L=10 $\mu$ H (LQH32CN100K53)**



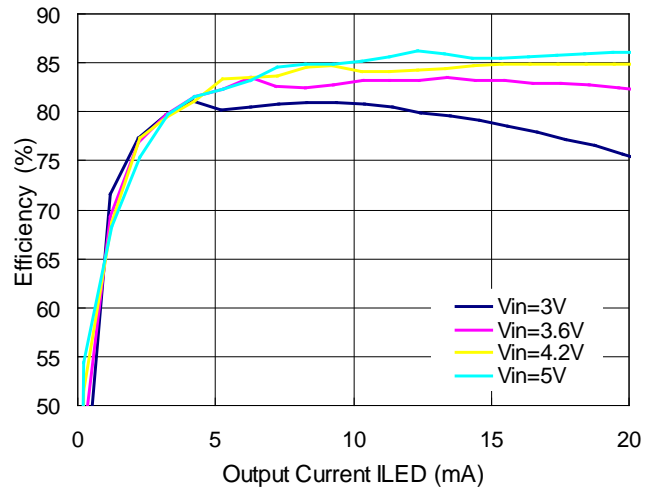
**5LED, L=22 $\mu$ H (LQH32CN220K53)**



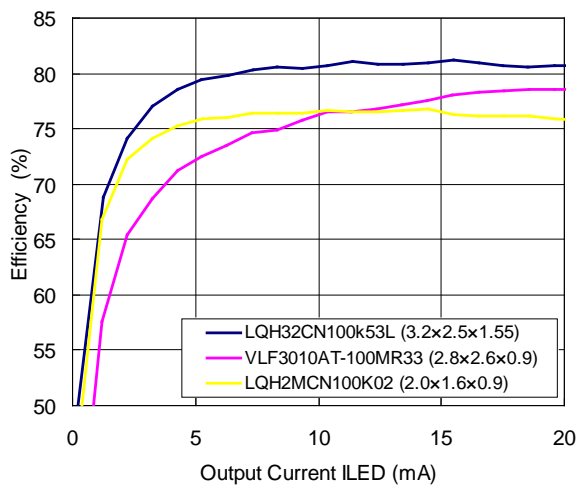
**6LED, L=10 $\mu$ H (LQH32CN100K53)**



**6LED, L=22 $\mu$ H (LQH32CN220K53)**



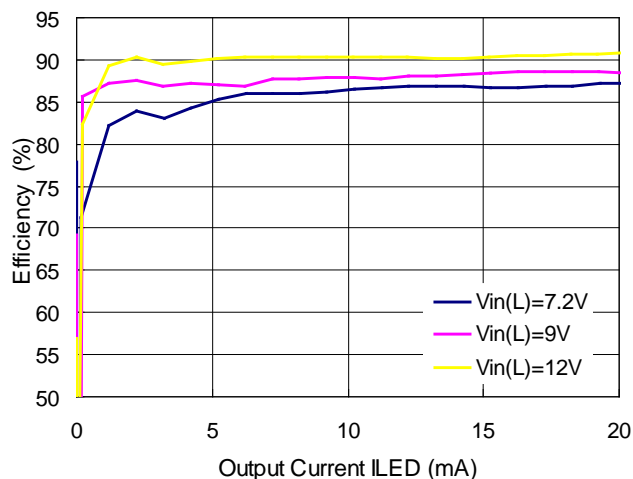
**6LED,  $V_{IN}=3.6V$**



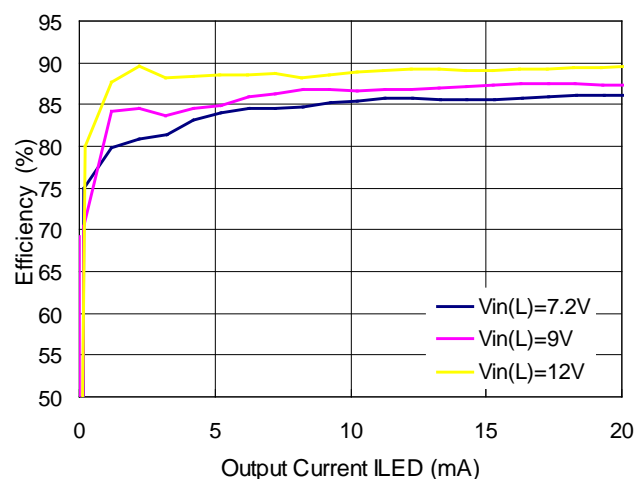


### Typical Applications with Using 5.5V or Greater

5LED,  $V_{IN(IC)}=3.6V$

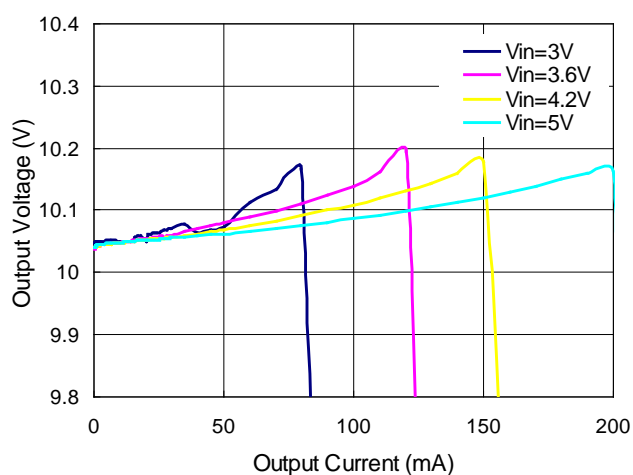


6LED,  $V_{IN(IC)}=3.6V$

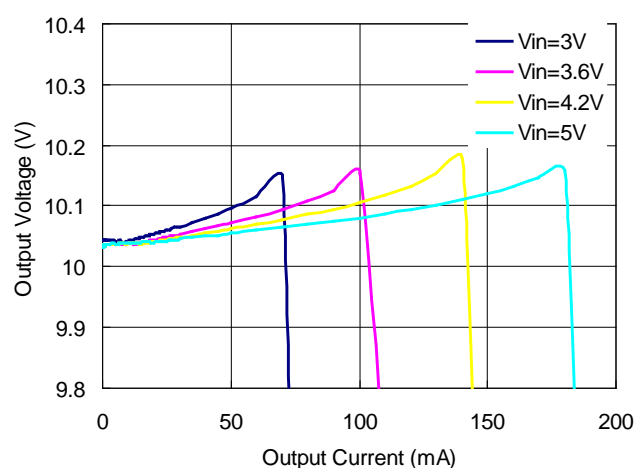


### 3) Output Voltage vs. Output Current (R1207N823A)

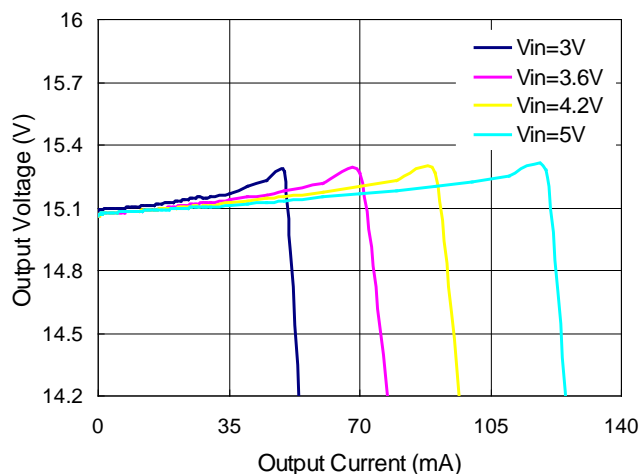
$V_{OUT}=10V$ ,  $L=10\mu H$  (LQH32CN100K53)



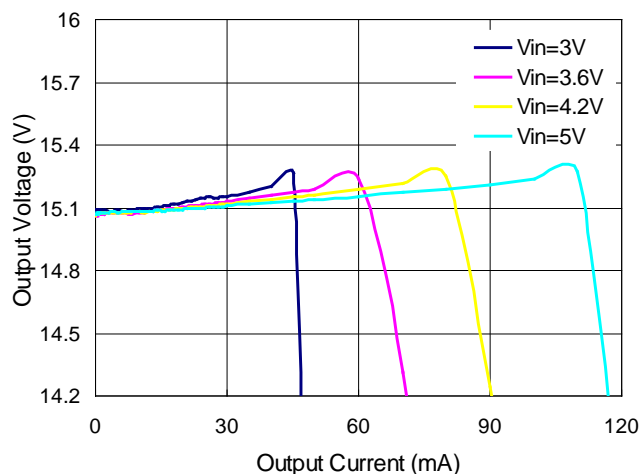
$V_{OUT}=10V$ ,  $L=22\mu H$  (LQH32CN220K53)



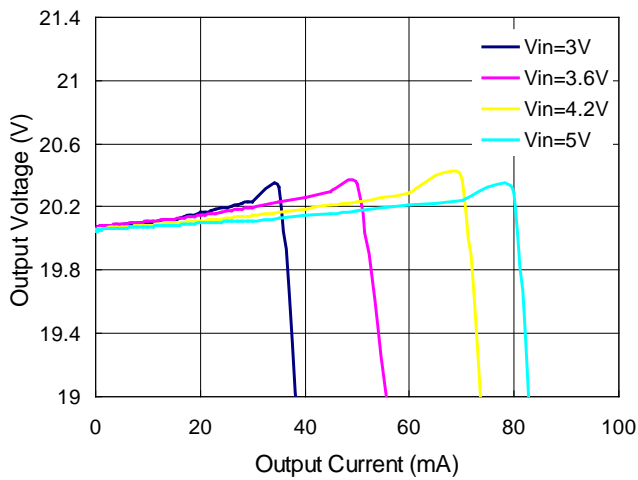
$V_{OUT}=15V$ ,  $L=10\mu H$  (LQH32CN100K53)



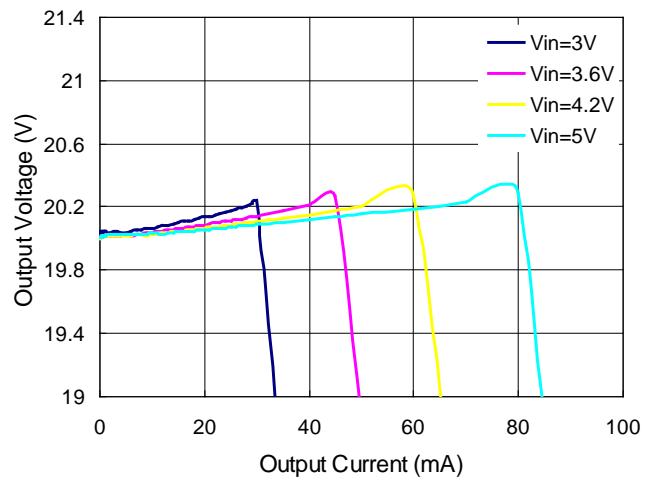
$V_{OUT}=15V$ ,  $L=22\mu H$  (LQH32CN220K53)



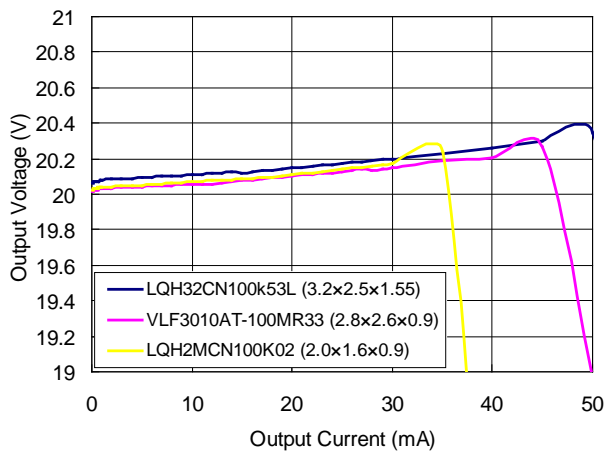
**V<sub>OUT</sub>=20V, L=10μH (LQH32CN100K53)**



**V<sub>OUT</sub>=20V, L=22μH (LQH32CN220K53)**

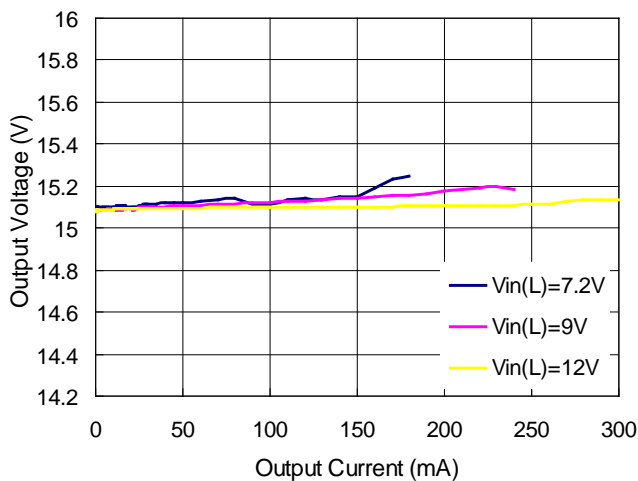


**V<sub>OUT</sub>=20V, V<sub>IN</sub>=3.6V**

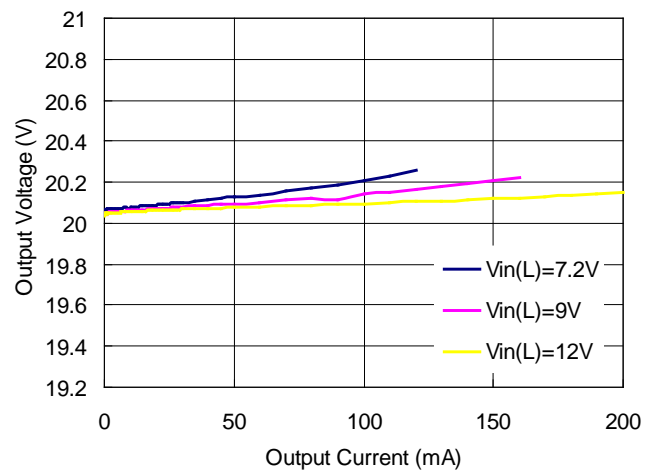


### Typical Applications with Using 5.5V or Greater

**V<sub>OUT</sub>=15V, L=10μH (LQH32CN100K53)**

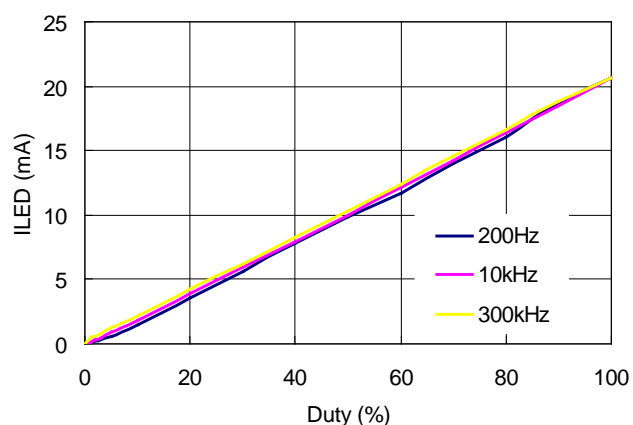


**V<sub>OUT</sub>=20V, L=10μH (LQH32CN100K53)**



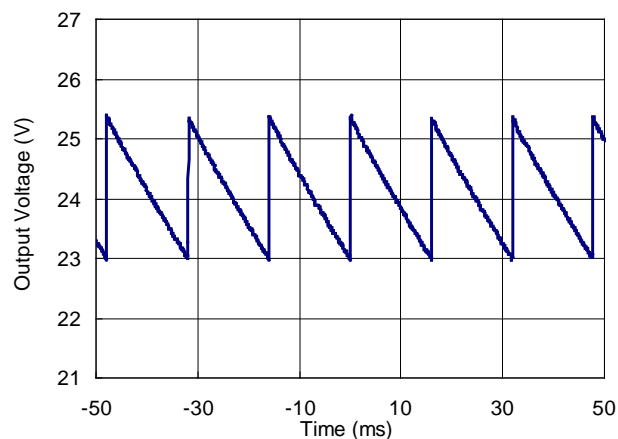
## 4) Maxduty vs. ILED

R1207N823B/C



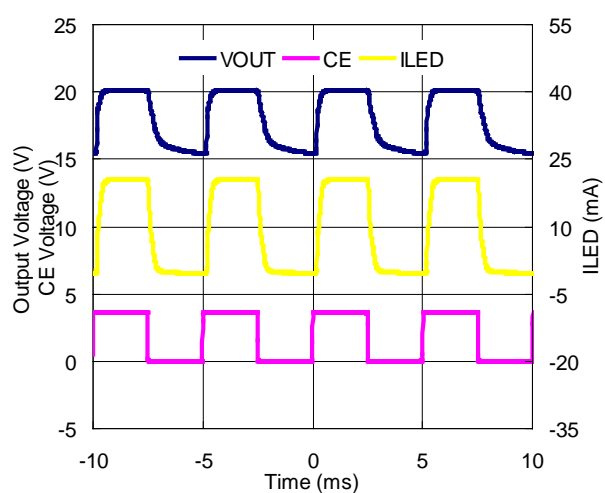
## 5) OVP Output Waveform

R1207N823B/C

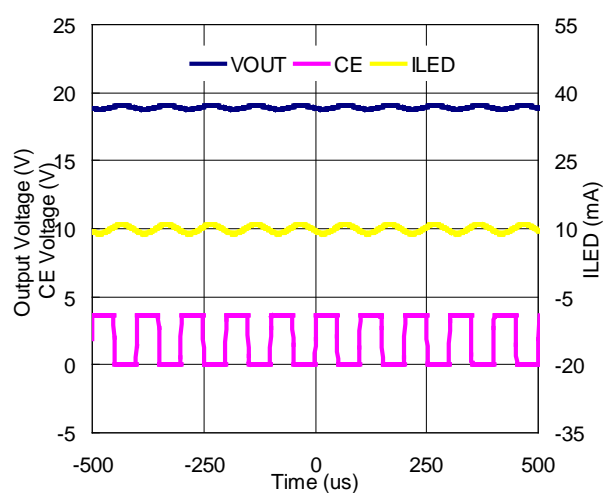


## 6) Waveform (6LED)

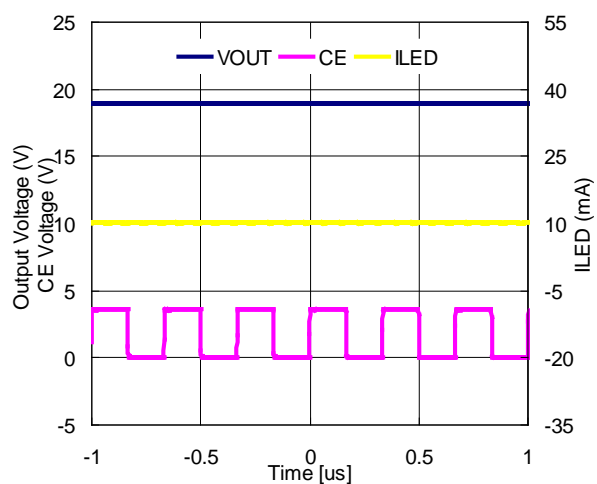
R1207N823B/C (CE Freq=200Hz)



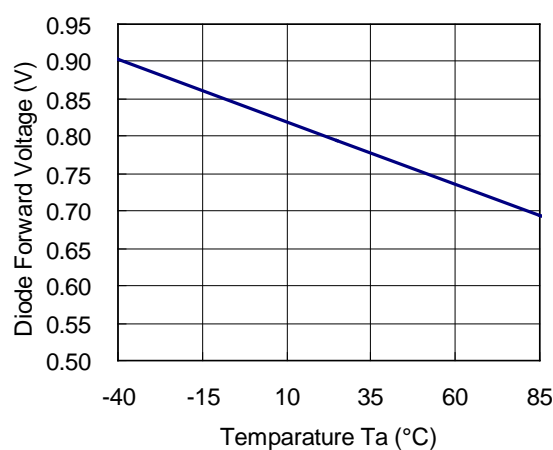
R1207N823B/C (CE Freq=10KHz)



R1207N823B/C (CE Freq=300KHz)



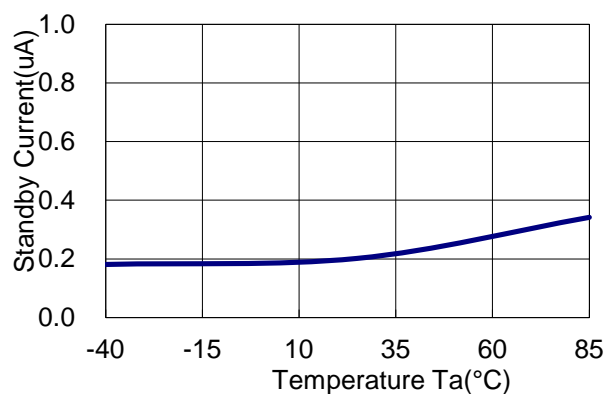
## 7) Diode Forward Voltage vs. Temperature



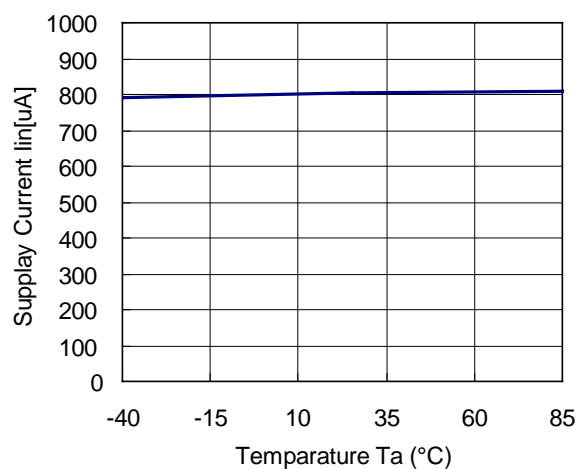
## R1207N

NO.EA-298-190808

### 8) Standby Current vs. Temperature

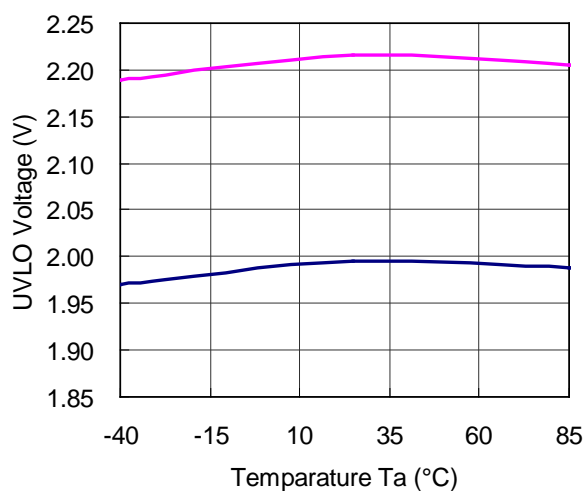


### 9) Supply Current vs. Temperature

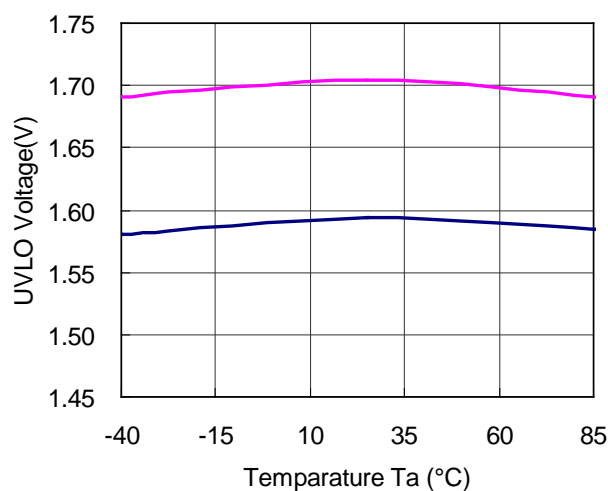


### 10) UVLO Output Voltage vs. Temperature

R1207N8xxA

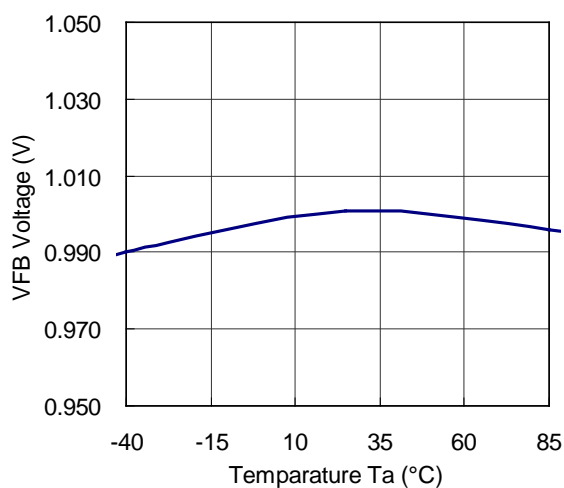


R1207N8xxB

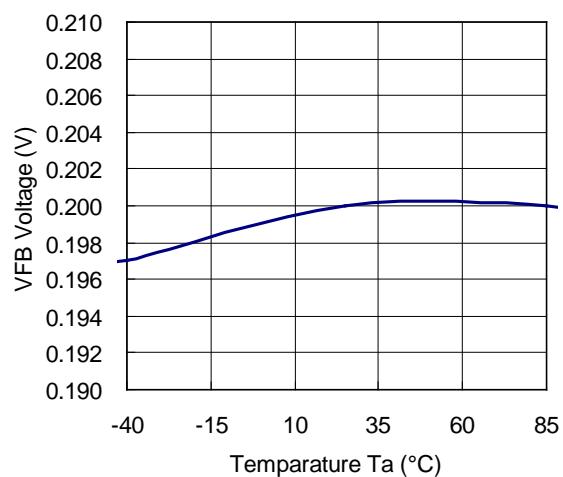


### 11) VFB Voltage vs. Temperature

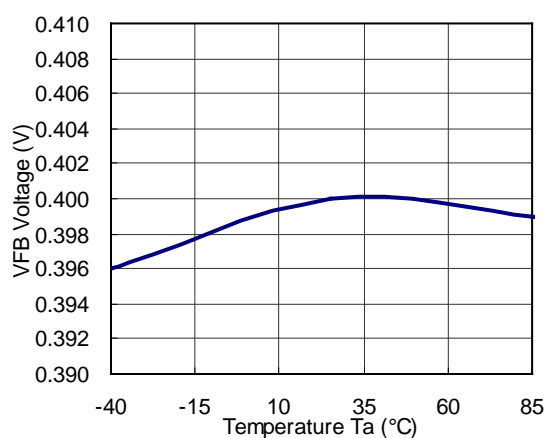
R1207N8xxA



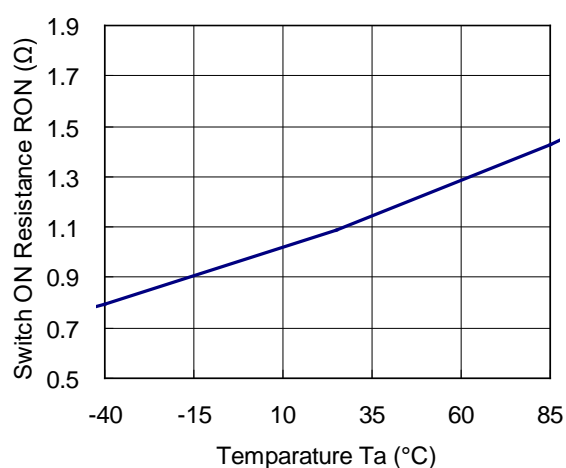
R1207N8xxB



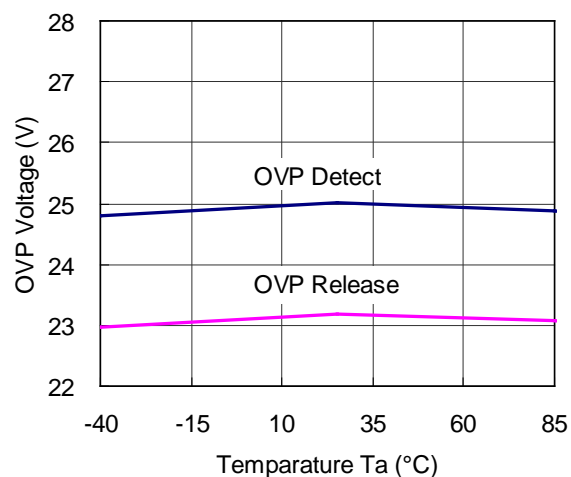
R1207N8xxC



12) Switch ON Resistance RON vs. Temperature

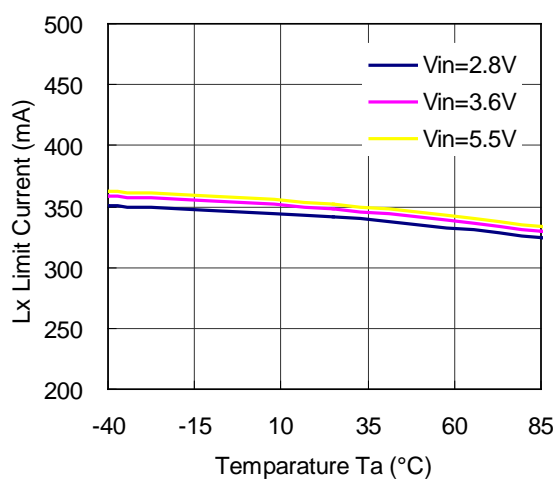


13) OVP Voltage vs. Temperature

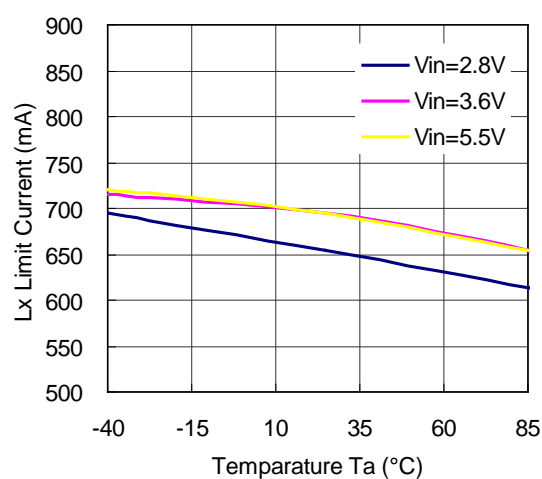


14) Lx Current Limit vs. Temperature

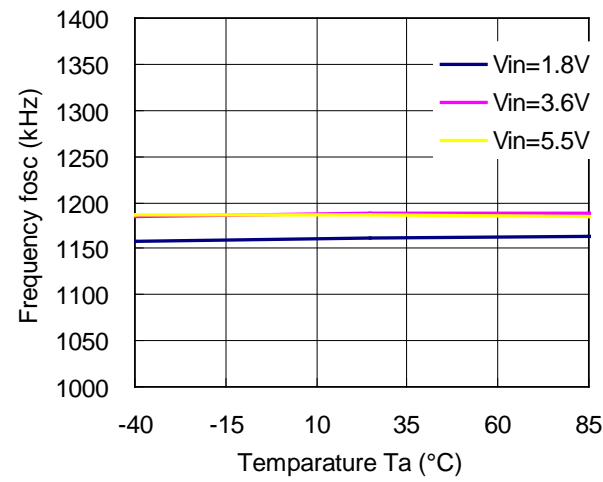
R1207N81xx



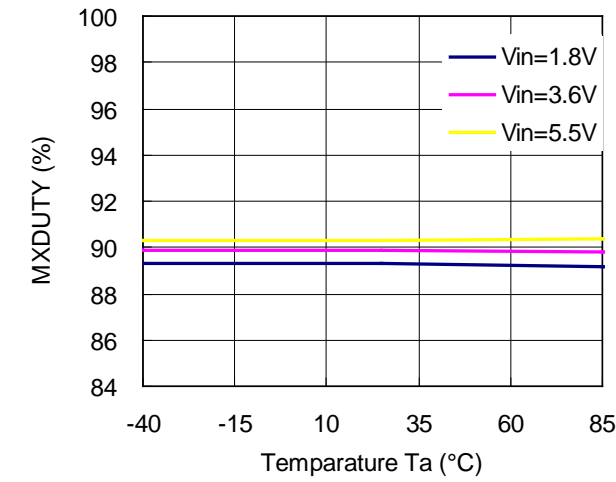
R1207N82xx



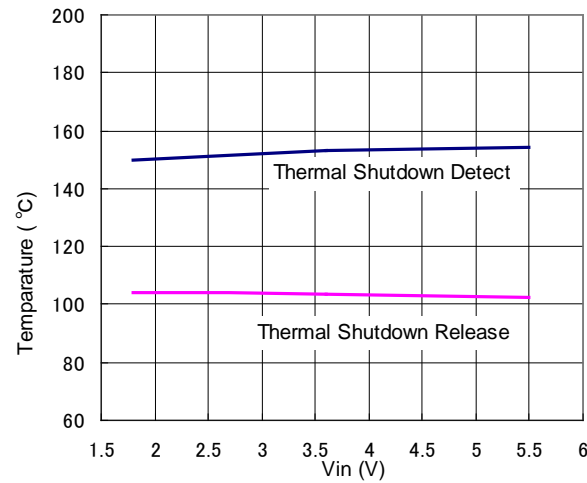
15) Oscillator Frequency vs. Temperature



16) Maxduty vs. Temperature



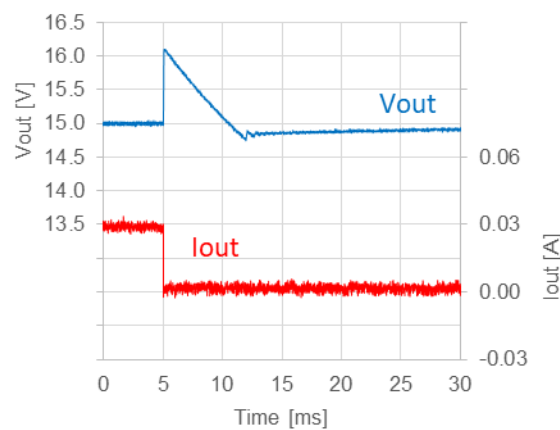
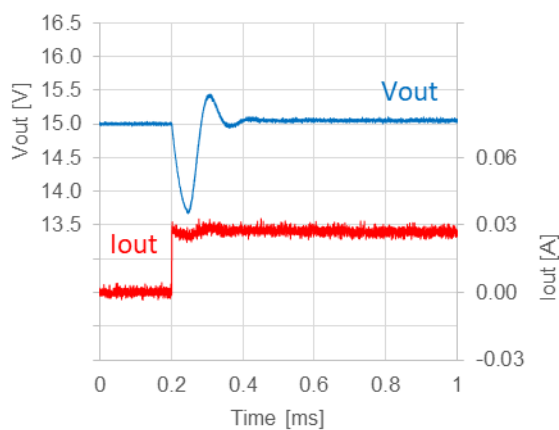
17) Thermal Shutdown Detect / Release Temperature vs. Input Voltage



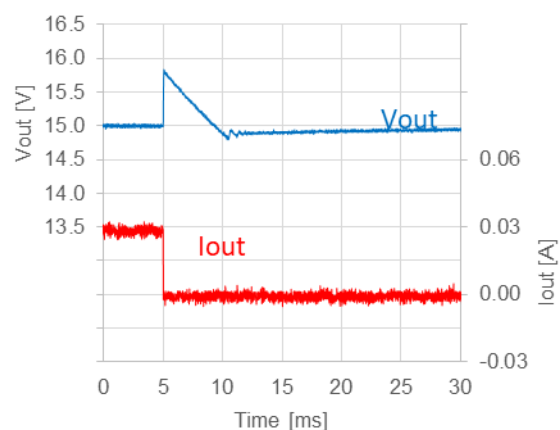
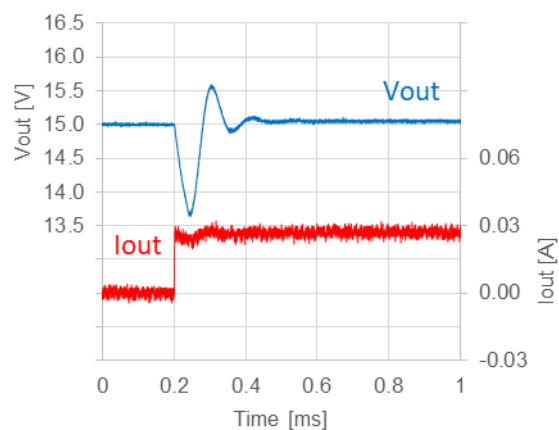
**18) Load Transient Response**

$V_{IN} = 3.6\text{ V}$ ,  $V_{OUT} = 15\text{ V}$   $I_{OUT} = 0\text{ mA} \Leftrightarrow 30\text{ mA}$

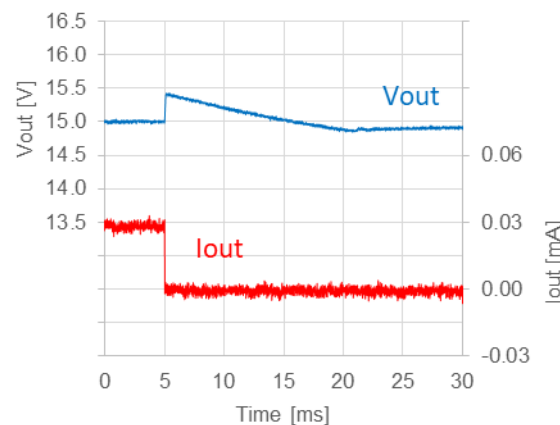
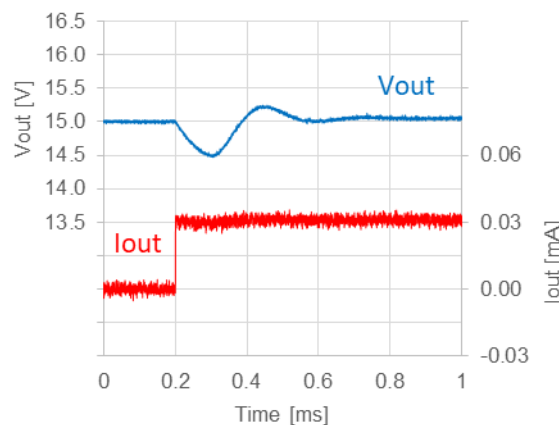
$L = 10\text{ }\mu\text{H}$  Setting : Table 3-A



$L = 22\text{ }\mu\text{H}$  Setting : Table 3-A



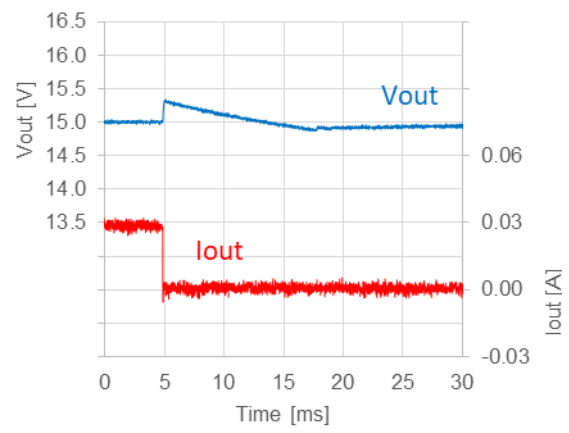
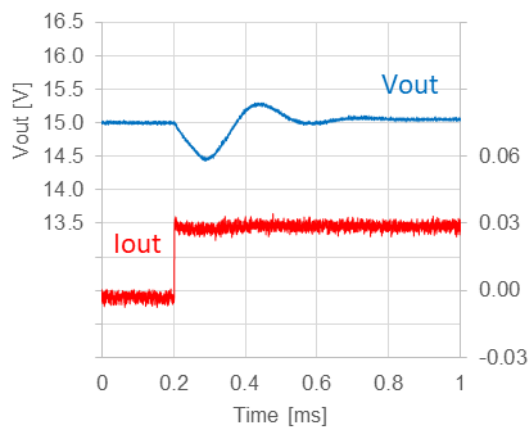
$L = 10\text{ }\mu\text{H}$  Setting : Table 3-B



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**R1207N**NO.EA-298-190808

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L = 22  $\mu$ H Setting : Table 3-B



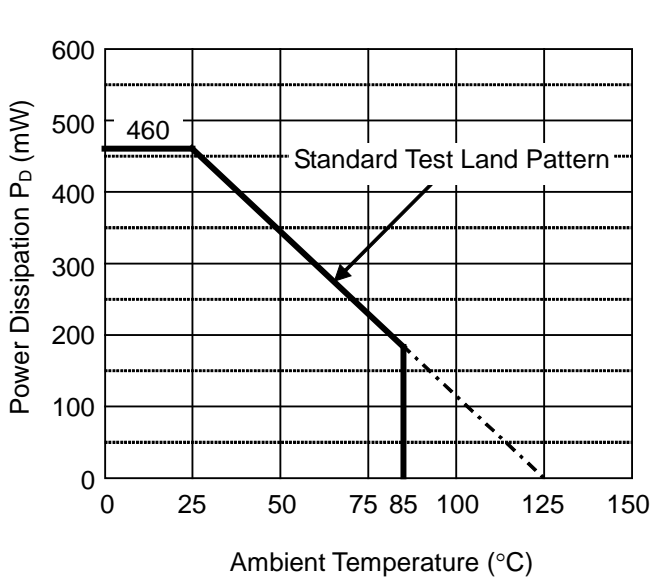
The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following conditions are used in this measurement.

Measurement Conditions

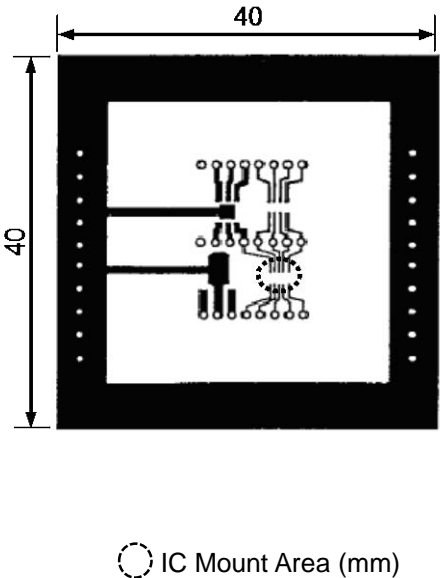
	Standard Test Land Pattern
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Double-Sided Board)
Board Dimensions	40 mm × 40 mm × 1.6 mm
Copper Ratio	Top Side: Approx. 50% Bottom Side: Approx. 50%
Through-holes	φ 0.5 mm × 44 pcs

Measurement Result (Ta = 25°C, Tjmax = 125°C)

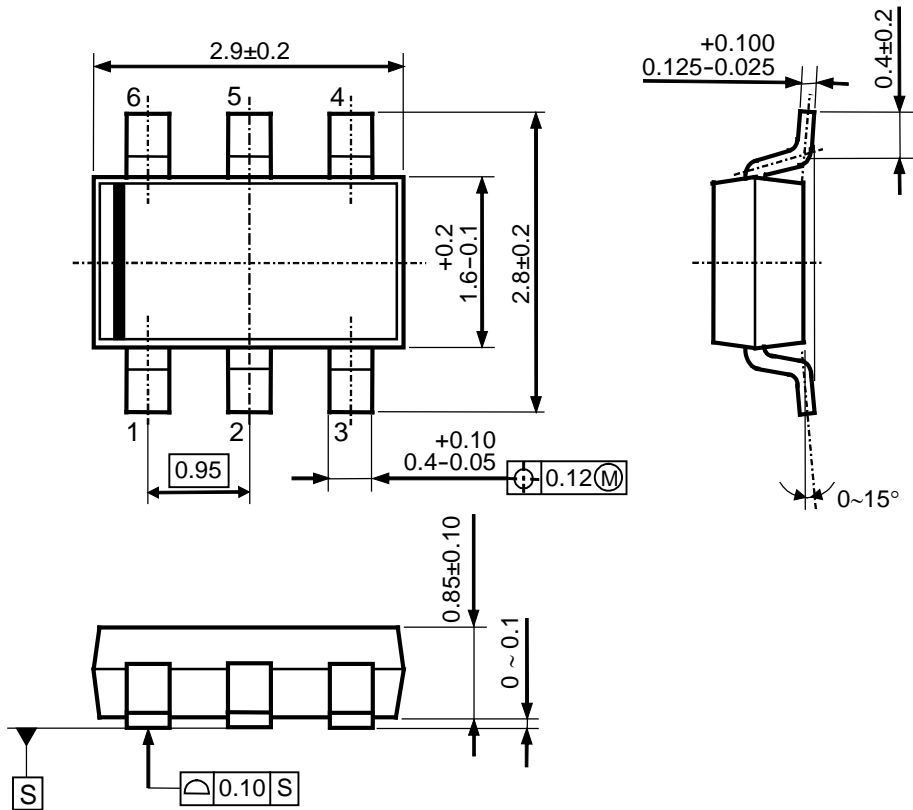
	Standard Test Land Pattern
Power Dissipation	460 mW
Thermal Resistance	$\theta_{ja} = (125 - 25^{\circ}\text{C}) / 0.46 \text{ W} = 217^{\circ}\text{C/W}$ $\theta_{jc} = 40^{\circ}\text{C/W}$



Power Dissipation vs. Ambient Temperature



Measurement Board Pattern



TSOT-23-6 Package Dimensions (Unit: mm)



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8. The X-ray exposure can influence functions and characteristics of the products. Confirm the product functions and characteristics in the evaluation stage.
9. WLCSP products should be used in light shielded environments. The light exposure can influence functions and characteristics of the products under operation or storage.
10. There can be variation in the marking when different AOI (Automated Optical Inspection) equipment is used. In the case of recognizing the marking characteristic with AOI, please contact our sales or our distributor before attempting to use AOI.
11. Please contact our sales representatives should you have any questions or comments concerning the products or the technical information.



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